11:200 1725

TRAN	NSMITTAL O	Docket No. 15574								
In Re Application Of: Hiroshi SAKAI, et al.										
Serial No.		Filing Date	Xaminer	Group Art Unit						
10	0/063,915	May 23, 2002	Kevin L . McHenry	1725						
Title: SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING										
S	SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED									
		Commis	Address to: ssioner for Patents .O. Box 1450 ria, VA 22313-1450							
_		37	CFR 1.97(b)							
1. The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.										
		37	CFR 1.97(c)							
2. 🔀	The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:									
	★ the statem	nent specified in 37 CFR 1.97(e	e);							
		OR		;						
	☐ the fee se	et forth in 37 CFR 1.17(p).								

	SURE STATEMENT	Docket No. 15574									
In Re Application: Hiroshi SAKAI, et al.											
Serial No.	Filing Date May 23, 2002	Examiner	Group Art Unit								
10/063,915	May 23, 2002	Kevin L . McHenry	1725								
SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED											
Payment of Fee (Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p)) A check in the amount of is attached.											
 The Director is hereby authorized to charge and credit Deposit Account No. 19-1013/SSMP as described below. Charge the amount of Credit any overpayment. Charge any additional fee required. 											
Certificate of	Transmission by Facsimile*	Certificate of Mailing b	y First Class Mail								
	ent and authorization to charge deposit mile transmitted to the United States Office (F:	I certify that this document and fee is being deposited on October 9, 2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.									
	Signature	Signature Paul J. Esatto, Jr.									
Typed or Printed N	ame of Person Signing Certificate	Typed or Printed Name									
	y only be used if paying by ignature PHY & PRESSER	Dated: October 9, 2003									
cc:											



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hiroshi SAKAI, et al. Examiner: Kevin L. McHenry

Serial No.: 10/063,915 Art Unit: 1725

Filed: May 23, 2002 Docket: 15574

For: SOLDER PASTE PRINTING METHOD Dated: October 9, 2003

AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICH

WIRING PATTERNS ARE FORMED

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R §§1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

- 1. Japanese Laid-Open Patent Application No. 5-96842, dated April 20, 1993;
- 2. Japanese Laid-Open Patent Application No. 11-1325, dated January 6, 1999;

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 9, 2003.

Dated: October 9, 2003

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- 3. Japanese Laid-Open Patent Application No. 9-62146, dated March 7, 1997;
- 4. Japanese Laid-Open Patent Application No. 11-347789, dated December 21, 1999; and
- 5. Japanese Laid-Open Patent Application No. 11-300492, dated November 2, 1999.

The references listed above were cited in an Official Action dated August 26, 2003 received from the Japanese Patent Office. Applicants are submitting copies of the above references, together with an English translation of the Examiner's comments regarding the references from the Official Action. Please note that the other references cited in the Official Action, namely, Japanese Laid-Open Patent Application No. H10-217425, dated August 18, 1998 and Japanese Laid-Open Patent Application No. 2001-47601, dated February 20, 2001, were previously submitted in applicants' Information Disclosure Statement dated August 7, 2003. The relevance of the references is described in the Official Action.

In compliance with the requirements of 37 C.F.R. §1.98(a)(3), as a concise statement of relevance, as it is presently understood by the individual designated in 37 C.F.R. §1.56(c) most knowledgeable about the content of the information, the undersigned attorney of record submits a translation of portions of an official action by a foreign examiner in which the references were cited. The relevance to the pending U.S. patent application is that the references were cited in a foreign patent application on the same subject matter. However, no independent analysis of the references, the accuracy of the statement of the foreign examiner or the claims of the foreign application under the laws of that country or the United States relative to the subject matter claimed in the present application has been made; the present understanding of the

contents thereof by the undersigned being based on the translation of the foreign examiner's comments submitted herewith.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R§1.97(c), the statement is enclosed.

Respectfully submitted,

Paul J/Esatto, Jr.

Registration No. 30,749

Scully, Scott, Murphy & Presser 400 Garden City Plaza Garden City, New York 11530 (516) 742-4343

PJE:AVS:jap



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hiroshi SAKAI, et al. Examiner: Kevin L. McHenry

Serial No.: 10/063,915 Group: 1725

Filed: May 23, 2002 Docket: 15574

For: SOLDER PASTE PRINTING METHOD Dated: October 9, 2003

AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON

WHICH WIRING PATTERNS ARE FORMED

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

STATEMENT PURSUANT TO 37 C.F.R. § 1.97(c)(1) and (e)(1)

Sir:

I hereby state that each item of information contained in this Information

Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 9, 2003.

Dated: October 9, 2003

Paul J/Esatto, Jr.

Accordingly, it is respectfully requested that the accompanying Information Disclosure Statement be considered with respect to the above-identified application.

Respectfully submitted,

Paul J. Esatto, Jr.

Registration No. 30,749

Scully, Scott, Murphy & Presser 400 Garden City Plaza Garden City, New York 11530 (516) 742-4343

PJE:AVS:jap

OTT	INTER OF	RMATION DISCLOSUE (Use several sheets if neces	OF CITATION	Docket Number (Optional) 15574 Applicant(s)		Application Number 10/063,915		
	ПЛГО	(Use several sheets if neces	SSary)	Hiroshi SAKAI, et	al.			
OCT 1	2083	6	••	Filing Date		Group Art Unit		
		<u> </u>		May 23, 2	2002]	1725	
EXAMINE		\$.		U.S. PATENT DOCUMENTS				
EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
				FOREIGN PATENT DOCUMENT	rs			
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES NO	
		5-96842	4/20/1993	Japan				
		11-1325	1/6/1999	Japan				
		9-62146	3/7/1997	Japan				
		11-347789	12/21/1999	Japan				
		11-300492	11/2/1999	Japan				
				OTHER DOCUMENTS (Include	ling Author, Title, L	Date, Pertinent Pa	ges, Etc.)	
				*				
EXAMINE	R			DATE CONSIDERED				
		al if citation considered, whethe		n conformance with MPEP Section 60 applicant.	9; Draw line throu	igh citation if not	in conformance and	
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